

UNITED STATES PATENT APPLICATION

FOR

A MICROCONTROLLER HAVING AN ON-CHIP HIGH GAIN AMPLIFIER

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5 **A MICROCONTROLLER HAVING AN ON-CHIP HIGH GAIN AMPLIFIER**  
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9 **CROSS REFERENCE TO RELATED DOCUMENTS**

10 This application is related to and claims priority benefit under 35  
11 U.S.C. §119(e) of U.S. Provisional Patent Application Serial No. 60/243,708, filed  
12 October 26, 2000 to Snyder, et al. which is hereby incorporated herein by  
13 reference. This application is also related to Serial No. \_\_\_\_\_, filed on the  
14 same date herewith, docket number CYPR-CD00199 to Kutz et al, entitled "Multiple  
15 Use of Microcontroller Pad" which is hereby incorporated by reference.  
16

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24 **FIELD OF THE INVENTION**

25 This invention relates generally to the field of integrated circuit  
26 microcontrollers. More particularly, this invention relates to a microcontroller having  
27 an integral analog amplifier.  
28  
29

## BACKGROUND OF THE INVENTION

Microcontrollers have become popular integrated circuits due to their versatility in applying computer controlling all types of devices. A high degree of versatility is, thus, prized in such microcontrollers. However, most such microcontrollers are digital devices designed to interface with external circuitry to adapt to an analog world. This often increases the cost of use of such devices due to the need to provide analog to digital and digital to analog conversion as well as providing separate circuitry to handle even simple analog functions.

## SUMMARY OF THE INVENTION

The present invention relates generally to an integrated circuit microcontroller. Objects, advantages and features of the invention will become apparent to those skilled in the art upon consideration of the following detailed description of the invention.

In one embodiment consistent with the present invention, a microcontroller includes a wide band, high gain amplifier on-chip capable of driving a 32 ohm speaker. The amplifier is controllable by the microcontroller processor to either enable or disable the amplifier and switch between multiple modes of power. In one embodiment, one or more such amplifiers are situated on the integrated circuit die at the corners of the die. This provides the advantages, in certain embodiments, of utilization of generally unused die area to provide the function of an audio amplifier driver to enhance the versatility of the microcontroller.

A microcontroller chip consistent with certain embodiments of the present invention includes a processor for executing program instructions. An array of configurable digital circuit blocks configured to perform a digital circuit function while an array of configurable analog circuit blocks configured to perform an analog circuit function, such analog circuit blocks are configured to produce an analog output signal. An on-chip CMOS analog amplifier having an input receiving the

1 analog output signal and producing an amplified output signal suitable for driving  
2 a loudspeaker external to the microcontroller chip.

3 In another embodiment consistent with the present invention, a  
4 microcontroller chip includes a processor for executing program instructions. An  
5 array of configurable circuit blocks configured to perform a circuit function, such  
6 circuit blocks configured to produce an analog output signal. An on-chip analog  
7 amplifier having an input receiving the analog output signal and producing an  
8 amplified output signal suitable for driving a loudspeaker external to the  
9 microcontroller chip.

10 The above summaries are intended to illustrate exemplary embodiments of  
11 the invention, which will be best understood in conjunction with the detailed  
12 description to follow, and are not intended to limit the scope of the appended  
13 claims.

#### 14 15 **BRIEF DESCRIPTION OF THE DRAWINGS**

16 The features of the invention believed to be novel are set forth with  
17 particularity in the appended claims. The invention itself however, both as to  
18 organization and method of operation, together with objects and advantages  
19 thereof, may be best understood by reference to the following detailed description  
20 of the invention, which describes certain exemplary embodiments of the invention,  
21 taken in conjunction with the accompanying drawings in which:

22 **FIGURE 1** is an exemplary layout of an integrated circuit die.

23 **FIGURE 2** is an overall block diagram of a microcontroller consistent with  
24 an exemplary embodiment of the present invention.

25 **FIGURE 3** illustrates a first switching arrangement for configuring a wirebond  
26 pad consistent with an embodiment of the invention.

27 **FIGURE 4** illustrates a second switching arrangement for configuring a  
28 wirebond pad consistent with an embodiment of the invention.

1           **FIGURE 5** is a block diagram showing the analog amplifier operating under  
2 control of the processor consistent with an embodiment of the invention.

3           **FIGURE 6** is a schematic illustrating a circuit arrangement for the analog  
4 amplifier consistent with an embodiment of the invention.

5           **FIGURE 7** illustrates the location of the analog amplifier according to an  
6 embodiment of the invention.

## 8                           **DETAILED DESCRIPTION OF THE INVENTION**

9           In the following detailed description of the present invention, numerous  
10 specific details are set forth in order to provide a thorough understanding of the  
11 present invention. However, it will be recognized by one skilled in the art that the  
12 present invention may be practiced without these specific details or with  
13 equivalents thereof. In other instances, well known methods, procedures,  
14 components, and circuits have not been described in detail as not to unnecessarily  
15 obscure aspects of the present invention.

16           While this invention is susceptible of embodiment in many different forms,  
17 there is shown in the drawings and will herein be described in detail specific  
18 embodiments, with the understanding that the present disclosure is to be  
19 considered as an example of the principles of the invention and not intended to limit  
20 the invention to the specific embodiments shown and described. In the description  
21 below, like reference numerals are used to describe the same, similar or  
22 corresponding parts in the several views of the drawings.

23           Turning now to **FIGURE 1**, an integrated circuit die 10 is illustrated. Die 10  
24 includes a plurality of wirebonding pads 14 (which are typically used for providing  
25 a wirebond or soldered electrical connection to the integrated circuit) situated  
26 around a periphery of the die 10. The pads 14 are separated by a separation  
27 distance 22 defined generally by the resolution of the circuit's manufacturing  
28 process and the circuit layout. Pads 14 are shown symmetrically disposed around  
29 the periphery in this illustration, but this is not generally a requirement. The pads

1 14 are also generally of a particular geometry, generally square with a minimum  
2 size 26 as shown, but other shapes are also used.

3 In the classic manufacturing process, an array of such dies are produced on  
4 a wafer of silicon. The dies are then separated from one another by cutting or  
5 breaking at a scribe line. During this process, the corner areas 30 of the die have  
6 historically been exposed to substantial amounts of mechanical stress and may  
7 fracture or break in the separation process. However, gradual improvements in the  
8 technology of separation of the dies has substantially lessened the stress and  
9 incidence of fractures in this region.

10 In order to maximize the versatility of the circuit arrangement of the present  
11 invention, a microcontroller 100 as illustrated in **FIGURE 2** utilizes one or more  
12 multi-purpose pads 114. Microcontroller 100 includes a processor 120 that can be  
13 programmed for a specified purpose by or for a user. Program instructions for  
14 carrying out such a specified purpose, along with information defining a  
15 configuration of circuitry contained on the microcontroller 100 is stored in various  
16 forms of memory represented as 122. A plurality of digital circuits are provided to  
17 form configurable digital blocks 124. These configurable digital blocks 124 can  
18 include gates, counters, buffers, latches, decoders, encoders, registers, flip-flops,  
19 timers, etc. that can be user configured in any suitable arrangement to implement  
20 a user's desired circuit configuration. Similarly, a plurality of analog circuits are  
21 provided to form configurable analog blocks 130. These configurable analog  
22 blocks may include filters, amplifiers, switches, clippers, limiters, summers,  
23 buffers, etc. that can be interconnected in a suitable arrangement to implement the  
24 user's desired circuit configuration.

25 The inputs and outputs for the configurable digital blocks 124 and  
26 configurable analog blocks 130 are coupled to a plurality of configurable switches  
27 136 to be routed to the multi-purpose pad 114. These switches are programmed  
28 by the user or at manufacture through the processor 120 and can be arranged in  
29 a number of ways to provide multiple use of the pad 114 to provide a uni-directional  
30 or bi-directional signal path as illustrated. The memory 122 stores the configuration

1 information associated with the desired configuration. The switching arrangement  
2 illustrated in **FIGURE 3** is somewhat conceptual and can be implemented in any  
3 number of ways as illustrated in the co-pending application to Kutz et al. described  
4 above. **FIGURE 3 - 4** illustrate several techniques for implementation of such  
5 switching as described in the co-pending application to Kutz et al which is  
6 incorporated by reference.

7 **FIGURE 3** illustrates a first circuit arrangement that can be utilized to  
8 implement the switching function of configurable switches 136. In this  
9 embodiment, an electronic switch circuit 304 can be used. Switch circuit 304 can  
10 be realized with, for example, a plurality of CMOS analog switches with one side  
11 of each switch connected together at a common junction. Switch 304 is connected  
12 to an analog input 310, an analog output 314, a digital input 320 and a digital output  
13 326 - any of which can be connected to pad 114 depending upon the switch  
14 position. The switch position can be determined by a control bus 330 that serves  
15 to enable one of the desired connections (e.g., by selectively turning on one of the  
16 CMOS analog switches) and thus complete the circuit to pad 114. The switch can  
17 be configured under the control of the processor 120 as either analog or digital,  
18 input or output.

19 In another embodiment illustrated in **FIGURE 4**, an analog input (to the  
20 microcontroller through pad 114) can be selectively switched to 310 using an  
21 analog switch 404 operating under control of an analog in enable control line 410  
22 that turns switch 404 on or off as desired to implement a connection to pad 114.  
23 An analog output from the microcontroller 100 can be selectively provided using  
24 tristate buffer amplifier 414. The analog out signal at 314 to be supplied to pad 114  
25 is supplied to the non-inverting input of a voltage follower configured operational  
26 amplifier. The amplifier can be selectively enabled using tristate control at a tristate  
27 analog out enable line 420. Tristate control can similarly be used to control  
28 digital out signal 326 through a tristate inverter 424. The output of the tristate  
29 inverter 424 is connected to pad 114 and it can be effectively removed from the

1 circuit or switched on using tristate control applied by tristate digital out enable  
2 signal 430 to control whether or not the inverter is enabled or "tri-stated". Tristate  
3 control can similarly be used to control digital in signal 320 through a tristate  
4 inverter 436. The high impedance input of the tristate inverter 436 is connected to  
5 pad 114 and it can be effectively removed from the circuit or switched on using  
6 tristate control applied by tristate digital in enable signal 440 to control whether or  
7 not the inverter is enabled or disabled (tri-stated). In this embodiment, the pad 114  
8 is isolated from the circuitry within the microcontroller by the high impedance of a  
9 tristate controlled gate or an analog switch in the off position to thus prevent  
10 unnecessary loading. Again, the switching arrangement can be configured under  
11 the control of the processor 120 as either analog or digital, input or output.

12 Referring now to **FIGURE 5**, a portion of microcontroller 100 is illustrated in  
13 connection with a high gain analog amplifier 504 that receives an analog input  
14 signal from a circuit configured from configurable analog blocks 130, consistent  
15 with an embodiment of the present invention. In this embodiment, the on-chip  
16 analog amplifier is realized as a tristate CMOS power amplifier of more or less  
17 conventional CMOS op-amp design with high current output transistors. The  
18 amplifier 504 has variable power level (and may also have variable gain) and has  
19 its output connected to pad 114. As illustrated in **FIGURE 4** and the co-pending  
20 Kutz et al. application generally, pad 114 can be a multiple function wirebond pad  
21 capable of connection to digital circuits through gates 436 or 424 as well as analog  
22 amplifier 504. Processor 120 can enable or disable the analog amplifier through  
23 tristate control (or any other suitable mechanism) by enable line 510 and can  
24 control the power of the amplifier by power control line 516 in the preferred  
25 embodiment.

26 With reference to **FIGURE 6**, a more detailed, but nonetheless simplified,  
27 view of CMOS amplifier 504 is presented illustrating one embodiment for  
28 implementation of such an amplifier. Amplifier 504 preferably has one or more pre-  
29 amplifier stages shown as 602 which may be implemented as either single ended



1 or differential as shown. In the preferred embodiment, a total of three stages of  
2 amplification is provided in a more or less conventional CMOS op-amp  
3 configuration. The differential output of the pre-amplifier 602 drives the power  
4 amplifier stage represented by the remainder of the circuit of **FIGURE 6**. The  
5 power amplifier includes a differential output stage made up of transistors 606 and  
6 608 with gates driven by pre-amplifier 602. The gates of transistors 606 and 608  
7 are biased in a conventional manner using diode connected transistors 612 and  
8 614 in series with current sources 622 and 624 respectively with the gates attached  
9 at the junctions of the diode connected transistors and the current sources.

10 In addition to the above bias arrangement, a second set of current sources  
11 632 and 634 are switchably connected in parallel with current sources 622 and 624  
12 respectively. Current sources 632 and 634 are selectively enabled by power control  
13 line 516. When power control 516 is enabled, a pair of CMOS transistor switches  
14 642 and 644 close to place current source 632 in parallel with current source 622  
15 and current source 634 in parallel with current source 624, thus increasing the bias  
16 current to transistors 606 and 608 and increase the current gain thereof. In this  
17 manner, the power of the power amplifier can be selected to have a lower value to  
18 conserve power or a higher power to drive a greater load. In one embodiment, the  
19 output transistors 606 and 608 are sized to produce enough current to drive a 32  
20 ohm loudspeaker. The switching of the current drive to the output transistors can,  
21 of course, be extended to more current sources and switches to provide greater  
22 degrees of control over the amplifier's current gain. Tristate control (not illustrated)  
23 can be used to enable or disable the amplifier 504 under control of processor 120.

24 The amplifier 504 consistent with certain embodiments of the present  
25 invention provides a high drive level (e.g., suitable for driving an audio loudspeaker  
26 without additional parts) and low distortion embodied within a microcontroller die.  
27 Thus, the microcontroller can directly drive an audio loudspeaker, provide digital to  
28 analog converter buffering, provide buffering for on-chip or off chip filtering, provide  
29 buffering for other analog signal processing circuits as well as providing numerous  
30 other configurable applications as will occur to those skilled in the art.

1 Referring now to **FIGURE 7**, one or more of amplifiers 504 can be situated  
2 on the die 10 adjacent the corners 30 as illustrated. The technology for separating  
3 the individual integrated circuit die from wafers has progressed by use of sawing,  
4 laser cutting and other technologies has rendered the corners 30 much less  
5 susceptible to damage than in the past. Although this progress has been made,  
6 the corners still remain largely unused, most design guidelines forbid circuitry in the  
7 corners. Since the amplifiers 504 can take a significant amount of die area to  
8 realize, use of generally unused portions of the die provide an opportunity to  
9 minimize the impact of adding such amplifiers to the microcontroller circuit.  
10 Moreover, the corner-most wirebond pads are readily accessed as output, power  
11 or ground pads for the amplifiers in certain embodiments.

12 While the invention has been described in conjunction with specific  
13 embodiments, it is evident that many alternatives, modifications, permutations and  
14 variations will become apparent to those skilled in the art in light of the foregoing  
15 description. Accordingly, it is intended that the present invention embrace all such  
16 alternatives, modifications and variations as fall within the scope of the appended  
17 claims.

18 What is claimed is: